

Application No. 10/603,924

Docket No. JCLA7109-R

In The Drawings:

Please replace the pending drawings of FIGs. 2, 3 and 4 with the drawings attached hereto
and labeled as "Replacement Sheets" in the top margin.

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Application No.: 10/603,924

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REMARKSPresent Status of the Application

Applicants have noted with appreciation that claims 1, 2, 4-7 and 31-41 have been allowed.

To rectify several deficiencies in the claims and the drawings, Applicants have amended claims 1, 2, 5, 33-34 and 37-40 and the drawings by correcting the typographical errors therein, and hereby respectfully submit that no new matter is introduced. Particularly, the erroneous spellings appearing in claims 2, 5, 33-34 and 37-40 have been corrected, and claim 1 has been amended to more clearly define that the chemical-mechanical polishing process is performed to remove a portion of the layer on the silicon wafer.

It is believed that these amendments do not change the consideration of patentability and thus should be acceptable.

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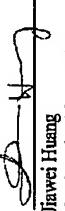
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CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1, 2, 4-7 and 31-41 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,
J.C. PATENTS


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Annotated Marked-up drawing

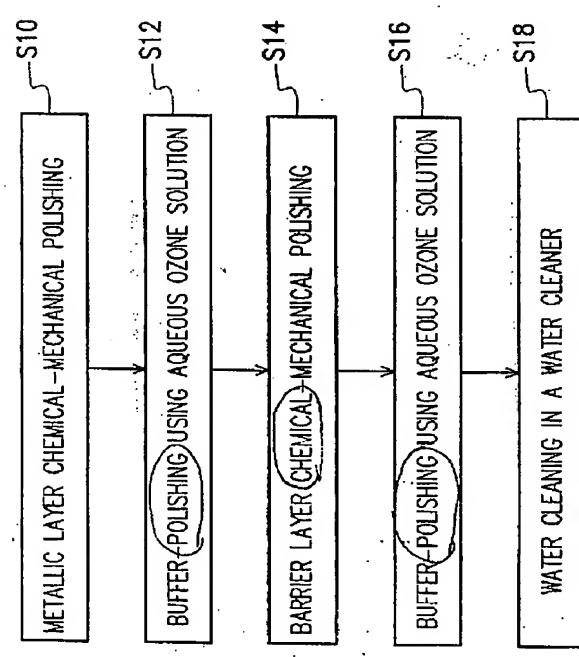


FIG. 2

Annotated Marked-up drawing

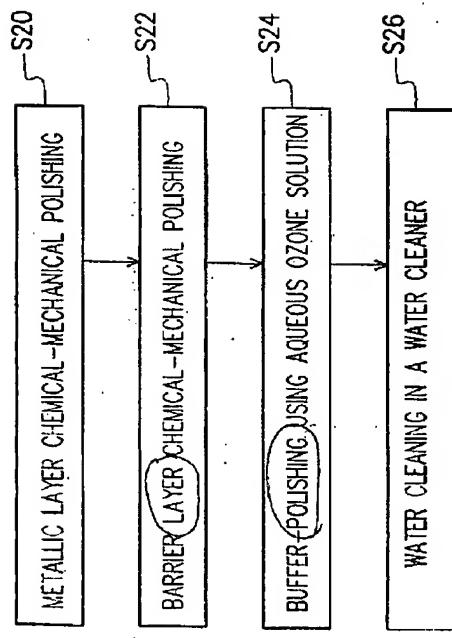


FIG. 3

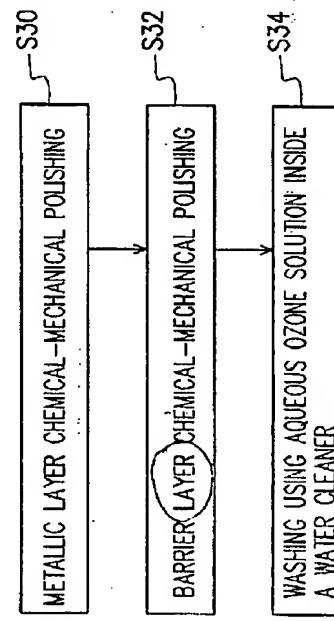


FIG. 4